XN04407 (XN4407)

Silicon PNP epitaxial planar transistor

For general amplification

■ Features

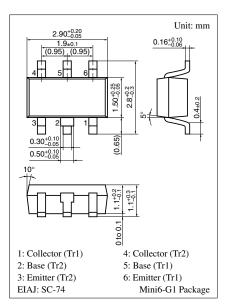
- Two elements incorporated into one package (Each transistor is separated)
- Reduction of the mounting area and assembly cost by one half

■ Basic Part Number of Element

• 2SB0709A (2SB709A) + 2SB0970 (2SB970)

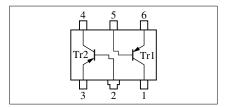
■ Absolute Maximum Ratings $T_a = 25$ °C

| Parameter | | Symbol | Rating | Unit | |
|-----------|------------------------------|------------------|-------------|------|--|
| Trl | Collector to base voltage | V_{CBO} | -60 | V | |
| | Collector to emitter voltage | V_{CEO} | -50 | V | |
| | Emitter to base voltage | V_{EBO} | -7 | V | |
| | Collector current | I_{C} | -100 | mA | |
| | Peak collector current | I_{CP} | -200 | mA | |
| Tr2 | Collector to base voltage | V_{CBO} | -15 | V | |
| | Collector to emitter voltage | V _{CEO} | -10 | V | |
| | Emitter to base voltage | V_{EBO} | -7 | V | |
| | Collector current | I_C | -500 | mA | |
| | Peak collector current | I_{CP} | -1 | A | |
| Total | Total power dissipation | P_{T} | 300 | mW | |
| | Junction temperature | T _j | 150 | °C | |
| | Storage temperature | T_{stg} | -55 to +150 | °C | |



Marking Symbol: ES

Internal Connection



Note) The part number in the parenthesis shows conventional part number.

\blacksquare Electrical Characteristics $~T_a = 25^{\circ}C \pm 3^{\circ}C$

• Tr1

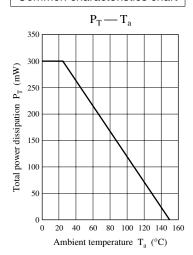
| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|---|----------------------|---|-----|-------|-------|------|
| Collector to base voltage | V _{CBO} | $I_C = -10 \mu A, I_E = 0$ | -60 | | | V |
| Collector to emitter voltage | V _{CEO} | $I_{\rm C} = -2 \text{ mA}, I_{\rm B} = 0$ | -50 | | | V |
| Emitter to base voltage | V _{EBO} | $I_E = -10 \ \mu A, \ I_C = 0$ | -7 | | | V |
| Collector cutoff current | I _{CBO} | $V_{CB} = -20 \text{ V}, I_E = 0$ | | | - 0.1 | μΑ |
| | I _{CEO} | $V_{CE} = -10 \text{ V}, I_B = 0$ | | | -100 | |
| DC current gain | h _{FE} | $V_{CE} = -10 \text{ V}, I_{C} = -2 \text{ mA}$ | 160 | | 460 | _ |
| Collector to emitter saturation voltage | V _{CE(sat)} | $I_C = -100 \text{ mA}, I_B = -10 \text{ mA}$ | | - 0.3 | - 0.5 | V |
| Collector output capacitance | C _{ob} | $V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$ | | 2.7 | | pF |
| Gain bandwidth product | f_T | $V_{CB} = -10 \text{ V}, I_E = 1 \text{ mA}, f = 200 \text{ MHz}$ | | 80 | | MHz |

• Tr2

| Parameter | Symbol | Conditions | Min | Тур | Max | Unit |
|---|----------------------|--|-----|--------|-------|------|
| Collector to base voltage | V_{CBO} | $I_C = -10 \mu A, I_E = 0$ | -15 | | | V |
| Collector to emitter voltage | V_{CEO} | $I_C = -1 \text{ mA}, I_B = 0$ | -10 | | | V |
| Emitter to base voltage | V_{EBO} | $I_E = -10 \ \mu A, I_C = 0$ | -7 | | | V |
| Collector cutoff current | I_{CBO} | $V_{CB} = -10 \text{ V}, I_E = 0$ | | | - 0.1 | μΑ |
| DC current gain * | h _{FE1} | $V_{CE} = -2 \text{ V}, I_{C} = -500 \text{ mA}$ | 100 | | 350 | _ |
| | h _{FE2} | $V_{CE} = -2 \text{ V}, I_C = -1 \text{ A}$ | 60 | | | |
| Collector to emitter saturation voltage | V _{CE(sat)} | $I_C = -400 \text{ mA}, I_B = -8 \text{ mA}$ | | - 0.16 | - 0.3 | V |
| Base to emitter saturation voltage | V _{BE(sat)} | $I_C = -400 \text{ mA}, I_B = -8 \text{ mA}$ | | - 0.8 | -1.2 | V |
| Collector output capacitance | C _{ob} | $V_{CB} = -10 \text{ V}, I_E = 0, f = 1 \text{ MHz}$ | | 22 | | pF |
| Gain bandwidth product | f_T | $V_{CB} = -10 \text{ V}, I_E = 50 \text{ mA}, f = 200 \text{ MHz}$ | | 130 | | MHz |

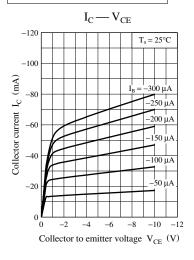
Note) *: Pulse test

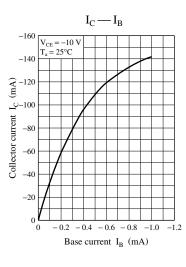
Common characteristics chart

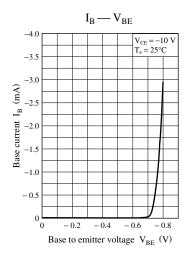


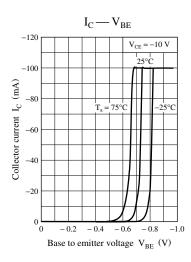
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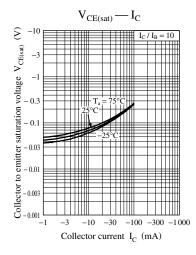
Characteristics chart of Tr1

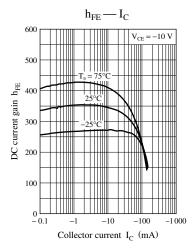


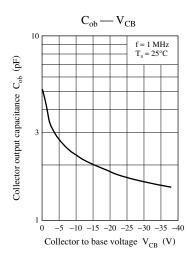






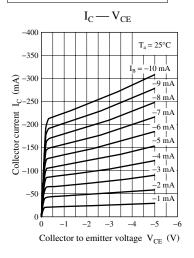


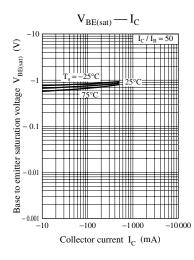


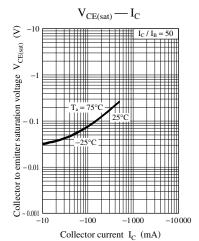


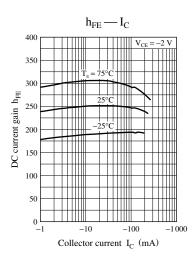
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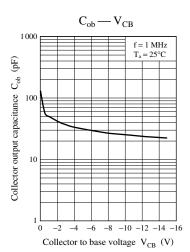
Characteristics chart of Tr2











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